Attorney Docket No. 81788.0267 Customer No.: 26021

## Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims**:

1-20. (Canceled)

- 21. (Currently Amended) A light emitting device comprising:
- a first lead:
- a second lead;
- a first semiconductor light emitting element mounted on said first lead;
- a semiconductor element mounted on said first lead;
- a first wire connecting said first semiconductor light emitting element and said second lead;
- a second wire connecting said semiconductor element and said second lead; and
- a silicone resin provided to enclose said first semiconductor light emitting element, said semiconductor element, at least a part of said first lead, at least a part of said second lead, and said first and second wires, and second said silicone resin having a hardness not lower than 50 in JISA value.
- 22. (Previously Presented) A light emitting device according to claim 21, further comprising a third wire connecting said first semiconductor light emitting element and said first lead,

wherein said first lead having a slit formed therein between a portion where said first semiconductor light emitting element is mounted and a portion where said third wire is connected.

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- 23. (Previously Presented) A light emitting device according to claim 21, wherein said semiconductor element is a second semiconductor light emitting element.
- 24. (Previously Presented) A light emitting device according to claim 23, wherein said first semiconductor light emitting element and said second semiconductor light emitting element are different in peak wavelength of light they emit.
- 25. (Previously Presented) A light emitting device according to claim 21, wherein said silicone resin has a pre-curing viscosity in the range not lower than 100 cp and not higher than 10000 cp.
- 26. (Currently amended) A light emitting device according to claim 21, wherein said silicone resin has a convex surface configuration.
- 27. (Previously Presented) A light emitting device according to claim 21, wherein said silicone resin has a hardness not higher than 90 in JISA value.
- 28. (Previously Presented) A light emitting device according to claim 21, further comprising a fluorescent element which is included in said silicone resin, absorbs light emitted from said first semiconductor light emitting element and releases light of a peak wavelength different from said light from said first semiconductor light emitting element.

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29. (New) A light emitting device according to claim 21, wherein said semiconductor element is a Zener diode connected in parallel opposite direction to said first light emitting element.

30. (New) A light emitting device according to claim 28, further comprising a third wire connecting said first semiconductor light emitting element and said first lead,

wherein said first lead having a slit formed therein between a portion where said first semiconductor light emitting element is mounted and a portion where said third wire is connected.

- 31. (New) A light emitting device according to claim 28, wherein said semiconductor element is a second semiconductor light emitting element.
- 32. (New) A light emitting device according to claim 28, wherein said first semiconductor light emitting element and said second semiconductor light emitting element are different in peak wavelength of light they emit.
- 33. (New) A light emitting device according to claim 28, wherein said silicone resin has a pre-curing viscosity in the range not lower than 100 cp and not higher than 10000 cp.
- 34. (New) A light emitting device according to claim 28, wherein said silicone resin has a convex surface configuration.

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- 35. (New) A light emitting device according to claim 28, wherein said silicone resin has a hardness not higher than 90 in JISA value.
- 36. (New) A light emitting device according to claim 28, wherein said semiconductor element is a Zener diode connected in parallel opposite direction to said first light emitting element.